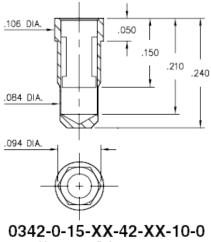


Product Number: 0342-0-15-01-42-27-10-0



Hex press-fit in .090±.002 plated thru hole

DATA SHEET

NO

Description:

0342 - Receptacle With No Tail Accepts .059-.063 diameter leads.

Packaging: Packaged in Bulk

Mill-Max Part Number	Shell Plating	Contact Plating	RoHS Compliant

0342-0-15-01-42-27-10-0

200 - 300 µ" Tin/Lead over Nickel

CONTACT:

Contact Used: #42, Power Contact Current Rating = 20 Amps

BERYLLIUM COPPER ALLOY 172 (UNS C17200) per **ASTM B 194**

Properties of BERYLLIUM COPPER:

- Chemical composition: Cu 98.1%, Be 1.9%
- Temper as stamped: TD01

Properties after heat treatment (TH01):

- Hardness: 36-43 Rockwell C
- Mechanical Life: 100 Cycles Min.
- Density: .298 lbs/in3
- Electrical Conductivity: 22% IACS*
- Resistance: 10 miliohms Max Operating Temperature: -55°C/+125°C
- Melting point: 980°C/865°C (liquidus/solidus)
- Stress Relaxation[†]: 96% of stress remains after 1,000 hours @ 100 °C ; 70% of stress remains after 1,000 hours @ 200 °C

*International Annealed Copper Standard, i.e. as a % of pure copper.

+Since BeCu loses its spring properties over time at high temperatures; it is rated for continuous use up to 150°C. For applications up to 300°C, Mill-Max offers many contacts in Beryllium Nickel. Contact Tech Support for more info.

Mechanical Data #42 Contact:

h	Insertion/Extraction Force with a Ø.061 (nominal) pin:							
	First Cycle		2nd & Subsequent Cycles					
	Insertion Force	Extraction Force	Insertion Force	Extraction Force				
	20N	6N	10N	6N				

30 µ" Gold over Nickel

SHELL MATERIAL:

BRASS ALLOY (UNS C36000) per ASTM B 16 Note: Swage Pins are Annealed

Properties of BRASS ALLOY:

- Chemical composition: Cu 61.5%, Zn 35.4%, Pb 3.1%⁺
- Hardness as machined: 80-90 Rockwell B
- Density: .307 lbs/in3
- Electrical conductivity: 26% IACS*
- Melting point: 900°C/885°C (liquidus/solidus)

+(3 to 4% lead is used to permit "free machining" and is permitted by EC Directive 2002/95Annex 6; so all pin materials are RoHS compliant)

*International Annealed Copper Standard, i.e. as a % of pure copper.

Certificate of Compliance:

This is to Certify that the product described above is manufactured to Mill-Max guality standards in accordance with all applicable specifications and drawing. Mill-Max certifies this product to be free from defects of materials and workmanship.

This Certificate of Compliance covers the following requirements:

- Dimensional (all features verified to be within tolerances described on the applicable drawing).
- Raw Material (materials and properties verified to be as described on the applicable drawing).
 Plating (platings as required, thickness verified, and performance including solderability per mil-standard).
- Performance (insertion extraction or other force requirements as described on the applicable drawing).

Compliance Statement for Registration, Evaluation, Authorization and Restriction of Chemicals (REACH) Reference:

1. Regulation EC No 1907/2006 of the European Parliament and of the Council of 18 December 2006, concerning the Registration, Evaluation, Authorization and Restriction of Chemicals (REACH)

2. ECHA, Candidate list of Substances of Very High Concern (SVHC) http://echa.europa.eu/reach_en.asp

Mill-Max is aware of the regulation and the SVHC list the EU published (referenced above). Mill-Max does not produce or sell any of the listed substances in their homogeneous form. These substances are not intentionally added during the manufacturing of any Mill-Max products. To our knowledge, our products do not contain the substances described on the ECHA SVHC list. Testing is not performed for materials and substances that were not intentionally added. No warranty, liability of indemnification is expressed or implied with this information. Mill-Max maintains surveillance of the ECHA website to obtain the latest information and periodically reviews the SVHC list for changes and additions.

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Mill-Max: 0342-0-15-01-42-27-10-0